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Vishay Semiconductors

High Performance Schottky Rectifier, 2 x 20 A

Base common cathode cathode common of cathode common cathode of common of cathode of cathod

VS-43CTQ...SPbF

cathode Anode

Anode

VS-43CTQ...-1PbF

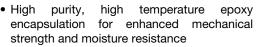
cathode Anode

Anode

PRODUCT SUMMARY					
Package	TO-263AB (D ² PAK), TO-262AA				
I _{F(AV)}	2 x 20 A				
V_R	80 V, 100 V				
V _F at I _F	0.67 V				
I _{RM} max.	11 mA at 125 °C				
T _J max.	175 °C				
Diode variation	Common cathode				
E _{AS}	7.50 mJ				

FEATURES

- 175 °C T_J operation
- Center tap configuration
- Low forward voltage drop





- High frequency operation
- Guard ring for enhanced ruggedness and long term reliability
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

DESCRIPTION

This center tap Schottky rectifier series has been optimized for low reverse leakage at high temperature. The proprietary barrier technology allows for reliable operation up to 175 °C junction temperature. Typical applications are in switching power supplies, freewheeling diodes, and reverse battery protection.

MAJOR RATINGS AND CHARACTERISTICS						
SYMBOL	CHARACTERISTICS	VALUES	UNITS			
I _{F(AV)}	Rectangular waveform	40	A			
V_{RRM}		80/100	V			
I _{FSM}	t _p = 5 µs sine	850	А			
V _F	20 A _{pk} , T _J = 125 °C (per leg)	0.67	V			
T _J	Range	-55 to +175	°C			

VOLTAGE RATINGS				
PARAMETER	SYMBOL	VS-43CTQ080SPbF VS-43CTQ080-1PbF	VS-43CTQ100SPbF VS-43CTQ100-1PbF	UNITS
Maximum DC reverse voltage	V_{R}	80	100	V
Maximum working peak reverse voltage	V_{RWM}	60	100	V

ABSOLUTE MAXIMUM RATINGS						
PARAMETER		SYMBOL	TEST COND	ITIONS	VALUES	UNITS
Maximum average per leg					20	
forward current See fig. 5	per device	I _{F(AV)}	50 % duty cycle at T _C = 135 °C, rectangular waveform		40	Α
Maximum peak one cycle non	Maximum peak one cycle non-repetitive		5 μs sine or 3 μs rect. pulse Following any rated		850	^
surge current per leg See fig. 7		I _{FSM}	10 ms sine or 6 ms rect. pulse	condition and with rated V _{RRM} applied	275	
Non-repetitive avalanche energy per leg		E _{AS}	$T_J = 25 ^{\circ}\text{C}, I_{AS} = 0.50 \text{A}, L = 60 \text{mH}$		7.50	mJ
Repetitive avalanche current p	per leg	I _{AR}	Current decaying linearly to zero in 1 μ s Frequency limited by T _J maximum V _A = 1.5 x V _B typical		0.50	А



VS-43CTQ...SPbF, VS-43CTQ...-1PbF Series

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ELECTRICAL SPECIFICATIONS					
PARAMETER	SYMBOL	TEST CO	NDITIONS	VALUES	UNITS
		20 A	T _{.1} = 25 °C	0.81	V
Maximum forward voltage drop per leg	V _{FM} ⁽¹⁾	40 A	1j=25 C	0.98	
See fig. 1	VFM (1)	20 A	T 105 °C	0.67	
		40 A	T _J = 125 °C	0.81	
Maximum reverse leakage current per leg	I _{RM} ⁽¹⁾	T _J = 25 °C	V _R = Rated V _R	1	mA
See fig. 2		T _J = 125 °C		11	
Threshold voltage	V _{F(TO)}	T T mayimum		0.71	V
Forward slope resistance	r _t	$T_J = T_J$ maximum		0.43	mΩ
Maximum junction capacitance per leg	C _T	$V_R = 5 V_{DC}$ (test signal range 100 kHz to 1 MHz), 25 °C		1480	pF
Typical series inductance per leg	L _S	Measured lead to lead 5 m	8.0	nH	
Maximum voltage rate of change	dV/dt	Rated V _R		10 000	V/µs

Note

 $^{(1)}\,$ Pulse width < 300 $\mu s,$ duty cycle < 2 %

THERMAL - MECHAN	THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER		SYMBOL	TEST CONDITIONS	VALUES	UNITS		
Maximum junction and storage	je	T _J , T _{Stg}		-55 to +175	°C		
Maximum thermal resistance, junction to case per leg		D	DC encystics	2.0			
Maximum thermal resistance, junction to case per package Typical thermal resistance, case to heatsink		R _{thJC}	DC operation	1.0	°C/W		
		R _{thCS}	Mounting surface, smooth and greased	0.50			
Approvimento weight				2	g		
Approximate weight				0.07	OZ.		
Manustina tanana	minimum			6 (5)	kgf · cm		
Mounting torque	maximum			12 (10)	(lbf \cdot in)		
			O	43CTQ080S			
Madden de ter			Case style TO-263AB (D ² PAK)	43CT0	Q100S		
Marking device			O I I TO 00044	43CTC	080-1		
			Case style TO-262AA	43CTC	43CTQ100-1		





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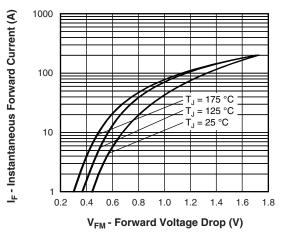


Fig. 1 - Maximum Forward Voltage Drop Characteristics (Per Leg)

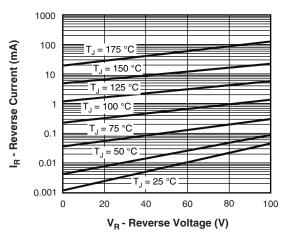


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage (Per Leg)

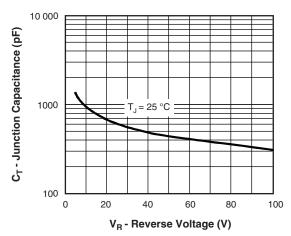


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage (Per Leg)

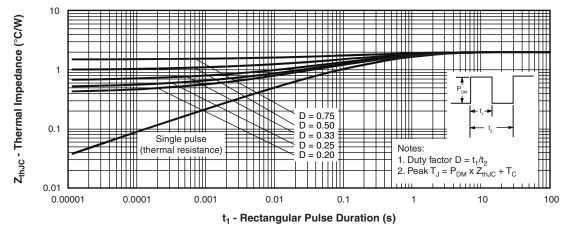


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics (Per Leg)

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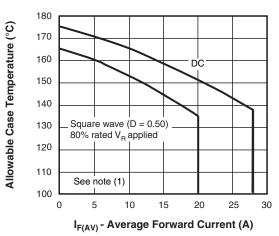


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current (Per Leg)

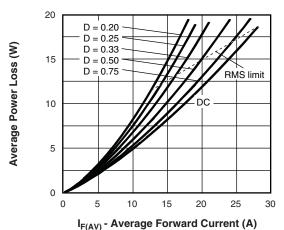


Fig. 6 - Forward Power Loss Characteristics (Per Leg)

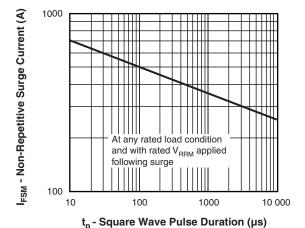


Fig. 7 - Maximum Non-Repetitive Surge Current (Per Leg)

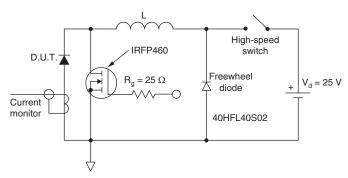


Fig. 8 - Unclamped Inductive Test Circuit

Note

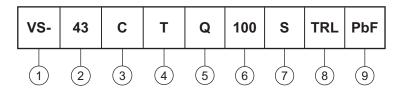
(1) Formula used: $T_C = T_J - (Pd + Pd_{REV}) \times R_{thJC}$; $Pd = Forward power loss = I_{F(AV)} \times V_{FM}$ at $(I_{F(AV)}/D)$ (see fig. 6); $Pd_{REV} = Inverse power loss = V_{R1} \times I_R$ (1 - D); I_R at $V_{R1} = 10$ V

VS-43CTQ...SPbF, VS-43CTQ...-1PbF Series

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ORDERING INFORMATION TABLE

Device code



1 - Vishay Semiconductors product

2 - Current rating (40 A)

Circuit configuration: C = common cathode

4 - T = TO-220

5 - Schottky "Q" series

6 - Voltage ratings - 080 = 80 V 100 = 100 V

7 - • S = D²PAK

• -1 = TO-262

None = tube (50 pieces)

• TRL = tape and reel (left oriented - for D²PAK only)

• TRR = tape and reel (right oriented - for D²PAK only)

9 - PbF = lead (Pb)-free

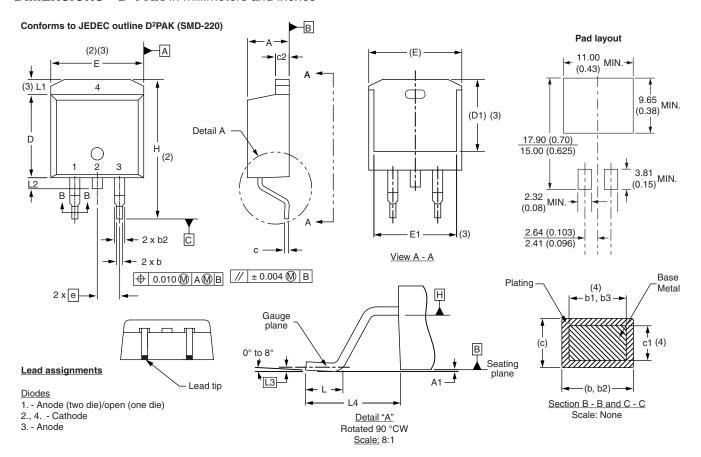
LINKS TO RELATED DOCUMENTS					
Dimensions <u>www.vishay.com/doc?95014</u>					
Part marking information	www.vishay.com/doc?95008				
Packaging information	www.vishay.com/doc?95032				
SPICE model	www.vishay.com/doc?95065				



Vishay Semiconductors

D²PAK, TO-262

DIMENSIONS - D²PAK in millimeters and inches



SYMBOL	MILLIN	IETERS	INC	NOTES	
STIVIDOL	MIN.	MAX.	MIN.	MAX.	NOTES
А	4.06	4.83	0.160	0.190	
A1	0.00	0.254	0.000	0.010	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
С	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2

SYMBOL	MILLIN	IETERS	INC	HES	NOTES
STWIBOL	MIN.	MAX.	MIN.	MAX.	NOTES
D1	6.86	8.00	0.270	0.315	3
Е	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
е	2.54	BSC	0.100 BSC		
Н	14.61	15.88	0.575	0.625	
L	1.78	2.79	0.070	0.110	
L1	-	1.65	-	0.066	3
L2	1.27	1.78	0.050	0.070	
L3	0.25 BSC		0.010	BSC	
L4	4.78	5.28	0.188	0.208	

Notes

- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- $^{(3)}\,$ Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inch

(7) Outline conforms to JEDEC outline TO-263AB

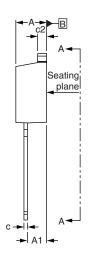
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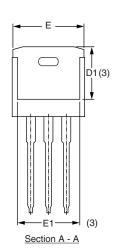
D²PAK, TO-262



DIMENSIONS - TO-262 in millimeters and inches

Modified JEDEC outline TO-262 (Datum A) (2) (3) E A (3) L1 D L2 B B B C C C C C C C A A (2) A A (2) A A (3) L2 A (4) A (5) A (6) A (7) A (8) A (9) A (10) A (10





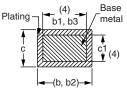


Lead assignments



<u>Diodes</u>
1. - Anode (two die)/open (one die)

2., 4. - Cathode 3. - Anode



Section B - B and C - C Scale: None

SYMBOL	MILLIN	MILLIMETERS		INCHES		
STINIBUL	MIN.	MAX.	MIN.	MAX.	NOTES	
Α	4.06	4.83	0.160	0.190		
A1	2.03	3.02	0.080	0.119		
b	0.51	0.99	0.020	0.039		
b1	0.51	0.89	0.020	0.035	4	
b2	1.14	1.78	0.045	0.070		
b3	1.14	1.73	0.045	0.068	4	
С	0.38	0.74	0.015	0.029		
c1	0.38	0.58	0.015	0.023	4	
c2	1.14	1.65	0.045	0.065		
D	8.51	9.65	0.335	0.380	2	
D1	6.86	8.00	0.270	0.315	3	
E	9.65	10.67	0.380	0.420	2, 3	
E1	7.90	8.80	0.311	0.346	3	
е	2.54	2.54 BSC) BSC		
L	13.46	14.10	0.530	0.555		
L1	-	1.65	-	0.065	3	
L2	3.56	3.71	0.140	0.146		

Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Controlling dimension: inches

(6) Outline conform to JEDEC TO-262 except A1 (maximum), b (minimum) and D1 (minimum) where dimensions derived the actual package outline



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